

Electronic Patent Application Fee Transmittal

Application Number:	10525996			
Filing Date:	28-Feb-2005			
Title of Invention:	Semiconductor wafer protection structure and laminated protective sheet for use therein			
First Named Inventor/Applicant Name:	Hideo Senoo			
Filer:	Kent E. Baldauf/Diane Paull			
Attorney Docket Number:	1217-050618			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	10	3	30
Total in USD (\$)				1770